

BEST AVAILABLE COPY

BYV



(19)

(11) Publication number: 6

Generated Document.

## PATENT ABSTRACTS OF JAPAN

(21) Application number: 60065407

(51) Intl. Cl.: H01L 21/302

(22) Application date: 29.03.85

<p>(30) Priority:</p> <p>(43) Date of application publication: 06.10.86</p> <p>(84) Designated contracting states:</p>	<p>(71) Applicant: TOSHIBA CORP</p> <p>(72) Inventor: KATSURA TOSHIHIKO ABE MASAYASU TAKAOKI KIYOSHI AOYAMA MASA HARU</p> <p>(74) Representative:</p>
------------------------------------------------------------------------------------------------------------------------	-------------------------------------------------------------------------------------------------------------------------------------------------------------------

(54) REACTIVE ION  
ETCHING APPRATUS

(57) Abstract:

**PURPOSE:** To enable the wafer surface to be etched by a method wherein a material to reduce the etching species of reactive gas in the ratio almost the

**CONSTITUTION:** The facing of an electrode 6 and an insulating sheet 10 are made larger than the outside diameter of a semiconductor 8 which a correcting ring 20 is provided between a step difference 12 due to the facing and the semiconductor wafer 8. Any material able to reduce etching species of reactive gas in the ratio subject to the difference between the etched materials but at least almost the same as that of any etched materials is applicable to the correcting ring 20. In such a constitution, there is a material to reduce the etching element in the peripheral part of semiconductor wafer as well as on the

semiconductor wafer therefore the part subject to uneven concentration of etching species (a) can be shifted to outside making the concentration of etching even on the semiconductor wafer 8. Resultantly, the semiconductor wafer 8 can be etched evenly.

COPYRIGHT: (C)1986,JPO&Japio

